

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10570668			
<b>Filing Date:</b>	06-Mar-2006			
<b>Title of Invention:</b>	SOI WAFER AND ITS MANUFACTURING METHOD			
<b>First Named Inventor/Applicant Name:</b>	Akihiko Endo			
<b>Filer:</b>	Sean Christophe Myers-Payne/Son T. Nguyen			
<b>Attorney Docket Number:</b>	P29124			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Notice of appeal	1401	1	540	540
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
Total in USD (\$)				1650